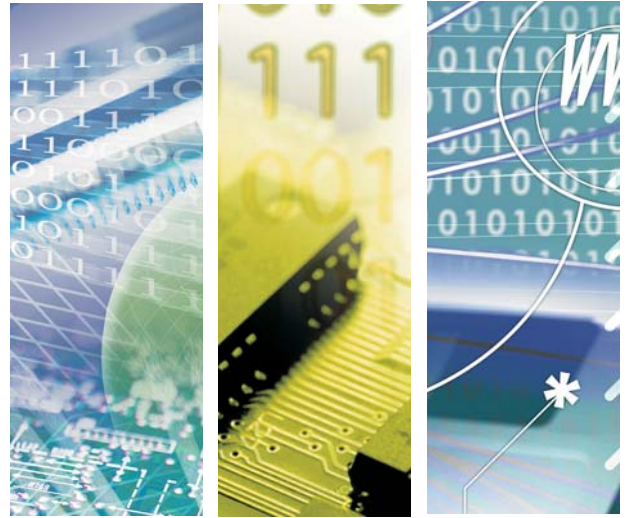
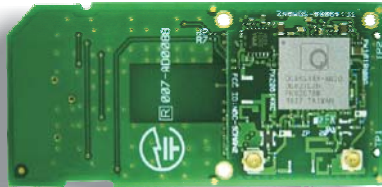




CEV906

802.11a/b/g/n Module with Bluetooth



CEV906

High Performance on 802.11a/b/g/n

Introduction of Products

Bointec CEV906 is a dual-band 802.11a/b/g/n plus Bluetooth SDIO card that is based on the CEV906 (Qualcomm Atheros AR6234). CEV906 is mechanically designed in a SD card form factor to provide customers with a vendor independent form factor.

The CEV906 is the only Freescale-recommended wireless connectivity solution for the i.MX 6 evaluation platform which includes integrated radio software support (driver and security supplicant). Integrates an external 5 GHz Front End Module (FEM) and is individually tuned to optimize WLAN performance.

Bointec provides superior product quality. CEV906 has validated that our design meets IEEE standards and each module is individually tested during the production process. This ensures that each of our products will perform to our published specification.

Product Highlight

- IEEE 802.11a/b/g/n conformity (2.4GHz & 5GHz)
- Supports IEEE802.11e, IEEE802.11d and IEEE 802.11h
- 2 spatial data stream system (2T2R)
- 2.4 GHz : Support 20 MHz bandwidth mode (Link rate 150 Mbps)
- 5 GHz : Support 20/40 MHz bandwidth mode (Link rate 300 Mbps)
- Link Data Rates
 - 802.11b/g 1-54 Mbps
 - 802.11a 6-54 Mbps
 - 802.11n 2.4GHz MCS0-7
 - 802.11n 5GHz MCS0/8-7/13
- Bluetooth 4.0 BR/EDR/LE Smart Ready compatible. Backward-compatible to 1.x, 2.x, 3.0.
- SDIO2.0 as the Wireless LAN host interface
- UART as the Bluetooth host interface
- +3.3V main power supply and selectable +1.8V/+3.3V IO power supply
- EU RoHS directive 2011/65/EC (Lead Free) compliant
- Selectable the ad-on antenna and the chip antenna (Option)
- SD card form factor



Specification

Chipset	Qualcomm Atheros AR6234
Host Interface	SDIO V 2.0 (4-bit, 1-bit)
Operating Voltage	3.30 VDC +/- 5%
Radio Specifications	802.11b/g/n 2.412 - 2.484 GHz / 802.11a/n 5.18 - 5.825 GHz
Baseband Specifications	CSMA/CA media access; DSSS, OFDM
Bluetooth Specifications	BT3.0+HS, BT4.0, Class 1.5
Operating Temperature	-10 to +70 degrees C
Dimensions	24.0 x 51.0 x 5.8 mm (W x H x D)
Connector Type	SD Card Edge 9 Pins / FFC Connector 20 Pins

General Specifications

On-Chip Functionality: Single-chip MAC/BB/RF/PALNA
Frequency Band: 2.4 GHz / 5 GHz
Network Standard: 802.11a, 802.11b, 802.11g, 802.11n(1-stream)
Modulation Modes: OFDM (64QAM, 16QAM, QPSK, BPSK), DSSS (CCK, DQPSK, DBPSK), DSSS-OFDM (64QAM, 16QAM, QPSK, BPSK)
Hardware Encryption: WEP, WPA/WPA2 (TKIP/AES-CCMP), WAPI
Quality of Service (QoS): WMM, WMM-PS, 802.11e

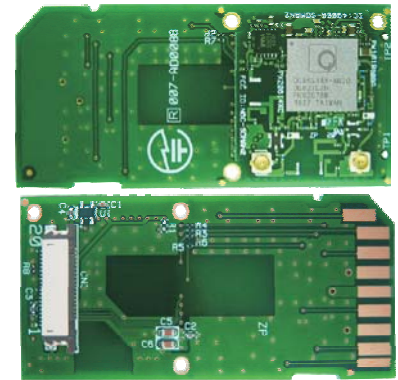
Interfaces

Communications: SDIO 2.0
Supported Data Rates:
IEEE 802.11b 1-11 Mbps
IEEE 802.11g 6-54 Mbps
IEEE 802.11a 6-54 Mbps
IEEE 802.11n HT20 6.5 - 65.0 Mbps
IEEE 802.11n HT40 13.5 - 135.0 Mbps
Bluetooth: BDR/EDR/LE
Physical Specifications: 24.0 x 51.0 x 5.8 mm (W x H x D)

Driver Support

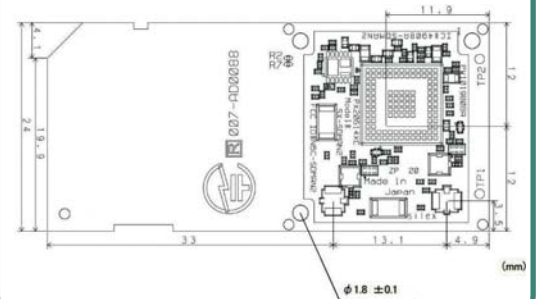
Linux
Android
Windows Embedded Compact 7
QNX Neutrino
Green Hills Intergrity

Product quick glance



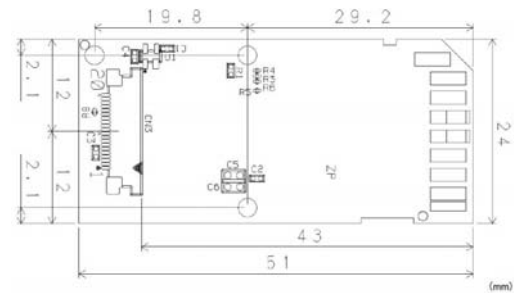
ME Drawing/placement

Top View



ME Drawing/placement

Bottom View



Ordering Information

PART NUMBER	DESCRIPTION
T.CFN906A-DK	CFN906A-DK, Single packed, development kit packed
TFGA-CEV90600-51	finished non packing, Silix, CEV906
TFGA-CFN905A0-52	finished packing, Silix, CFN906



TAIJET BOINTEC CO LTD
4F, # 114, Zhouzi St., Neihu-Taipei 11493, Taiwan
TEL: +886-2-2759-0081
WWW.BOINTEC.COM

Bointec Authorized Distributer

(C)TAIJET BOINTEC. All rights reserved. TAJET Bointec & the TAJET Bointec logo are the trademarks of TAJET Bointec, which may be registered in some jurisdictions. All other brands and product names are registered trademarks of their respective holders. Information supplied by TAJET Bointec is believed to be accurate and reliable. TAJET Bointec assumes no responsibility for any errors in this brochure. TAJET Bointec reserves the right, without notice, to make changed in product design or specifications.